Design according	: OBSAI System Spezifikation V 1.1
Approvals Underwriters Laboratories Inc.®	: c UL us with their respective ratings documented in file E 102079
Number of contacts	: up to 4
Contact spacing	: 3.00 mm
Clearance and creepage distances between contacts	: > 2.3 mm
Working current	: 23 A max. (OBSAI configuration) 20 A max. (fully loaded with power contacts)
Test voltage $U_{r.m.s.}$	: AC 1500 V min.
Contact resistance	: < 1 mΩ
Insulation resistance:	: > 10 GΩ
Temperature range	: - 55 °C ... + 125 °C
during reflow soldering	220 °C for 2 minutes, 260 °C max. short-term
Durability as per IEC 61 076-4-101	: *Performance level 2 = 250 mating cycles in total.* First 125 mating cycles, then 4 days gas test using 0.5 ppm SO_2 and 0.1 ppm H_2S (at 25 + 2 °C and 75 + 3 % humidity). Measurement of contact resistance. The remaining 125 mating cycles are subject to measurement of contact resistance and visual inspection. No abrasion of the contact finish through to the base material. No functional impairment.
Termination technique	
Male connectors	: Press-in or solder termination, suitable for (lead-free) pin-in-hole reflow soldering
Female connectors	: Press-in termination
Mating force	: max. 4 N / contact
Withdrawal force	: min. 0.5 N / contact
Materials	
Mouldings	: Thermoplastic resin, glass-fibre filled, UL 94-V0
Contacts	: Copper alloy
Contact surface	: Selectively gold plated (contact zone)
Contact styles	: Standard, leading, lagging
Packaging	
Tube	: Male and female connectors
Tape & Reel	: On request for male solder connectors